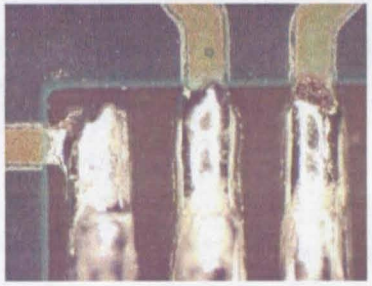
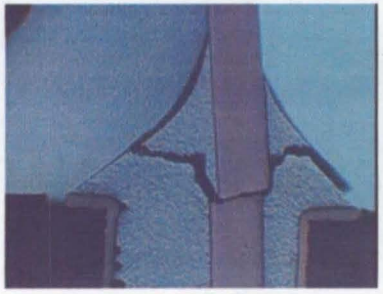
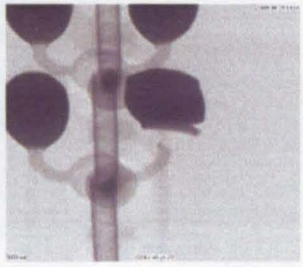
National Aeronautics and Space Administration (NASA)

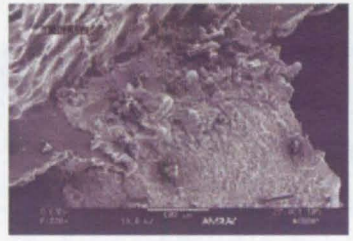
NASA-DoD Lead-Free Electronics Project

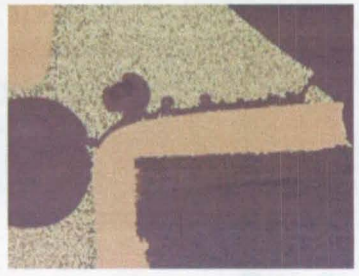
Eighteenth Annual Cleaner, Sustainable Industrial Materials & Processes (CSIMP) Workshop – March 18, 2008

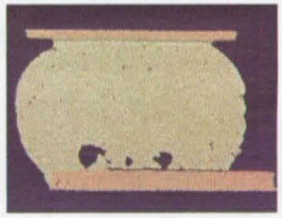


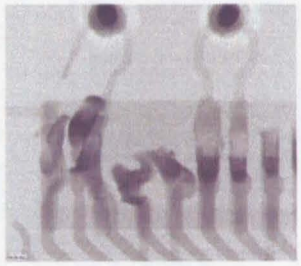


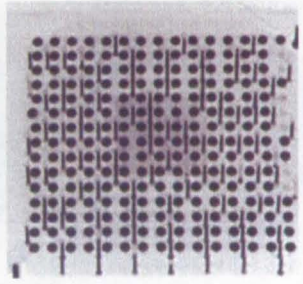












BAE SYSTEMS

Rockwell Collins

Honeywell

Raytheon

COM DEV

LOCKHEED MARTIN

calce

ITB inc

TEXAS INSTRUMENTS

BOEING

CELESTICA

HARRIS

TT APSCO

NIHON SUPERIOR

Testing project will build on the results from the JCAA/JGPP LFS Project

The primary technical objective of this project is to undertake comprehensive testing to generate information on failure modes/criteria to better understand the reliability of:

Packages (e.g., Thin Small Outline Package [TSOP], Ball Grid Array [BGA], Plastic Dual In-line Package [PDIP]) assembled and reworked with lead-free alloys

Packages (e.g., TSOP, BGA, PDIP) assembled and reworked with mixed (lead/lead-free) alloys.

Web Links:

NASA-DoD Lead-Free Electronics Project:
http://www.teerm.nasa.gov/projects/NASA_DODLeadFreeElectronics_Proj2.html

JCAA/JGPP Lead-Free Solder Project
http://www.teerm.nasa.gov/projects/LeadFreeSolderTestingForHighReliability_Proj1.html

Comparison of NASA-DoD LFE Project to predecessor JCAA/JG-PP LFS Project

Similarities

- Virtually identical test vehicle
- Procedures identical for most tests
- Same facility for assembly
- SN100C being used for wave soldering

Differences

- Test articles will be thermally aged after assembly
- Increased rework
- Increased solder mixing
- Mechanical shock test procedure
- Drop testing
- Immersion Ag surface finish for most test vehicles
  - Limited number will have ENIG
- SAC305 being used for reflow soldering
- SN100C being used for reflow soldering

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Rockwell Collins

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WARFARE CENTERS
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BAE SYSTEMS

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We never forget who we're working for™

your partner for soldering solution

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calce™

Raytheon

Honeywell

Interconnect PWB Solutions Inc.

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TEXAS INSTRUMENTS

U.S. AIR FORCE

Joint Test Protocol Endorsement

Endorsement signifies agreement that the JTP contains performance and technical requirements applicable to specific applications within programs, and provides the consensus needed to move forward with testing.

- Air Force - Electronic Engineer (WR-ALC/ENFM)
- Air Force - Director of Engineering (DOE) for the 312/326 Aeronautical Systems Wing (AESW); Wright-Patterson Air Force Base
- Headquarters - Air Force Space Command
- NASA - NEPP Program
- NASA-MSFC - Packaging, EEE Parts & Electrical Manufacturing Branch Chief
- MDA – PMP Program Lead
- NSWC Crane Division - 2M Project Manager
- NSWC Crane Division - 2M (Miniature/Microminiature) Electronics Technician
- NSWC Crane Division - Electronics Engineer, Testing: Printed Circuit Technologies Branch
- NSWC Crane Division - Materials Engineer; FA/MA Branch, Flight Systems Division
- BAE Systems - Principal Process Engineer
- Celestica - Director of Technology - IAD sector
- COM DEV - Director, Design Integrity
- General Dynamics - Design Assurance Engineering Manager
- Harris - Process Engineering Group Lead
- Lockheed Martin - Engineering Manager
- Nihon Superior - President of Nihon Superior
- Radiance Technologies, Inc. - AERI Program Manager
- Rockwell Collins - Director, Advanced Manufacturing Technology
- TT Apsco - Vice President and General Manager

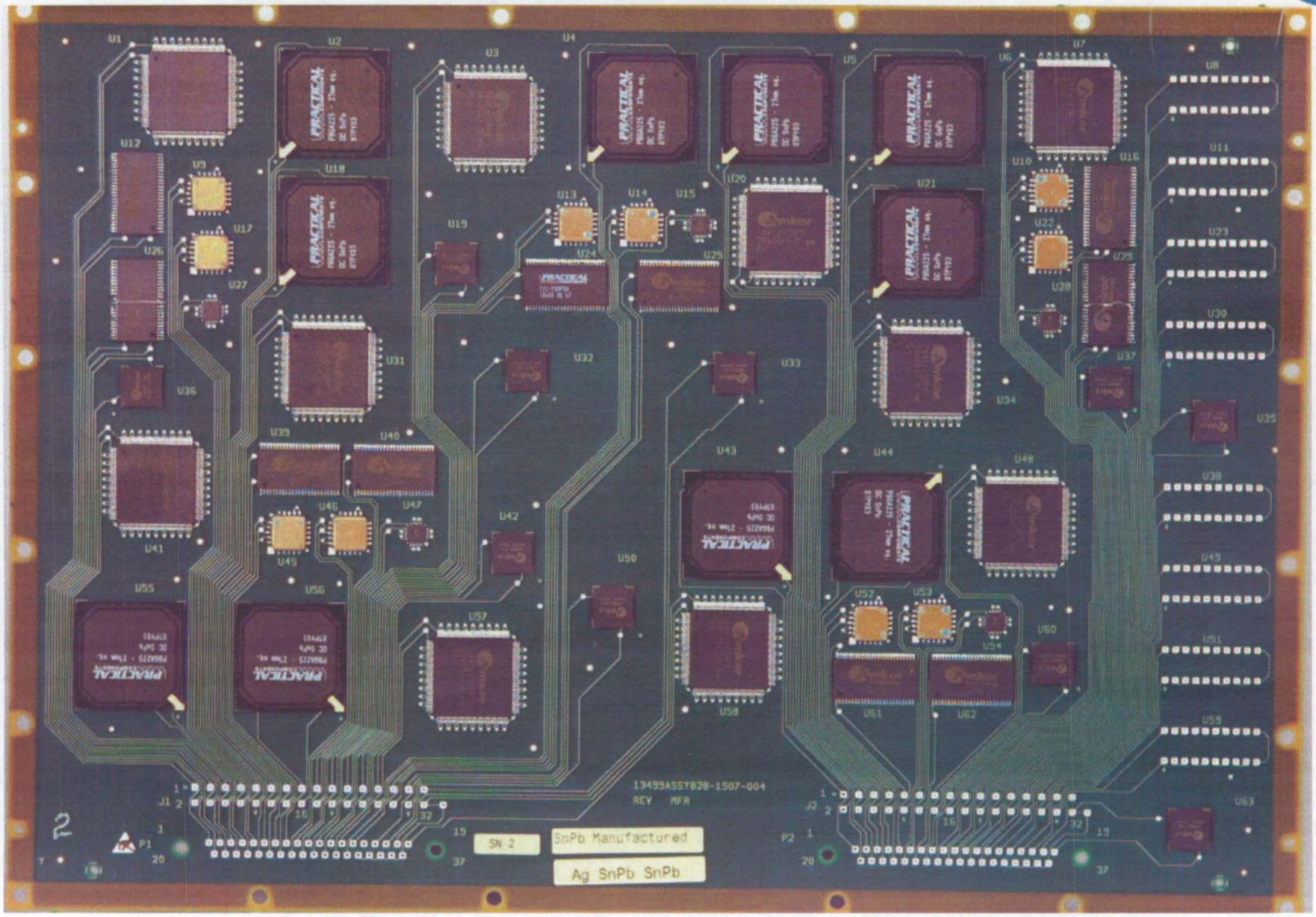
Lead-Free Solder Alloys

- SAC305 (Sn3.0Ag0.5Cu)
  - Surface mount assembly

    This alloy was chosen for reflow soldering because this particular solder alloy has shown the most promise as a primary replacement for tin-lead solder. The team decided that they wanted to select at least one "general purpose" alloy to be evaluated and it was determined that the SnAgCu solder alloy would best serve this purpose.

- SN100C (Sn0.7Cu0.05Ni+Ge)
  - Plated through hole
  - Surface mount assembly

    This alloy is commercially available and the general trend in industry has been switching to the nickel stabilized tin-copper alloy over standard tin-copper due to superior performance. In addition, this nickel-stabilized alloy does not require special solder pots and has shown no joint failures in specimens with over 4 years of service.


13499ASSY828-1507-004
REV MFR
SN 2
SnPb Manufactured
Ag SnPb SnPb

Component Finish/Solder Combinations Example

SnPb Manufactured				
Component	**Component Finish**	**Reflow Solder**	**Wave Solder**	**Board Finish**
BGA-225	SAC405	SnPb		Immersion Silver
BGA-225	SnPb	SnPb		
CLCC-20	SAC305	SnPb		
CLCC-20	SnPb	SnPb		
CSP-100	SAC105	SnPb		
CSP-100	SnPb	SnPb		
PDIP-20	NiPdAu		SnPb	
PDIP-20	Sn		SnPb	
QFN	Matte Sn	SnPb		
TQFP-144	Matte Sn	SnPb		
TQFP-144	SnPb Dip	SnPb		
TSOP-50	SnBi	SnPb		
TSOP-50	SnPb	SnPb		

Reflow Profile = SnPb
Preheat = ~ 120 seconds @140-183°C
Solder joint peak temperature = 225°C
Time above reflow = 60-90 sec
Ramp Rate = 2-3 °C/sec

Wave Profile = SnPb
Solder Pot Temperature = 250°C
Preheat Board T = 101°C
Peak Temperature = 144°C
Speed: 110 cm/min

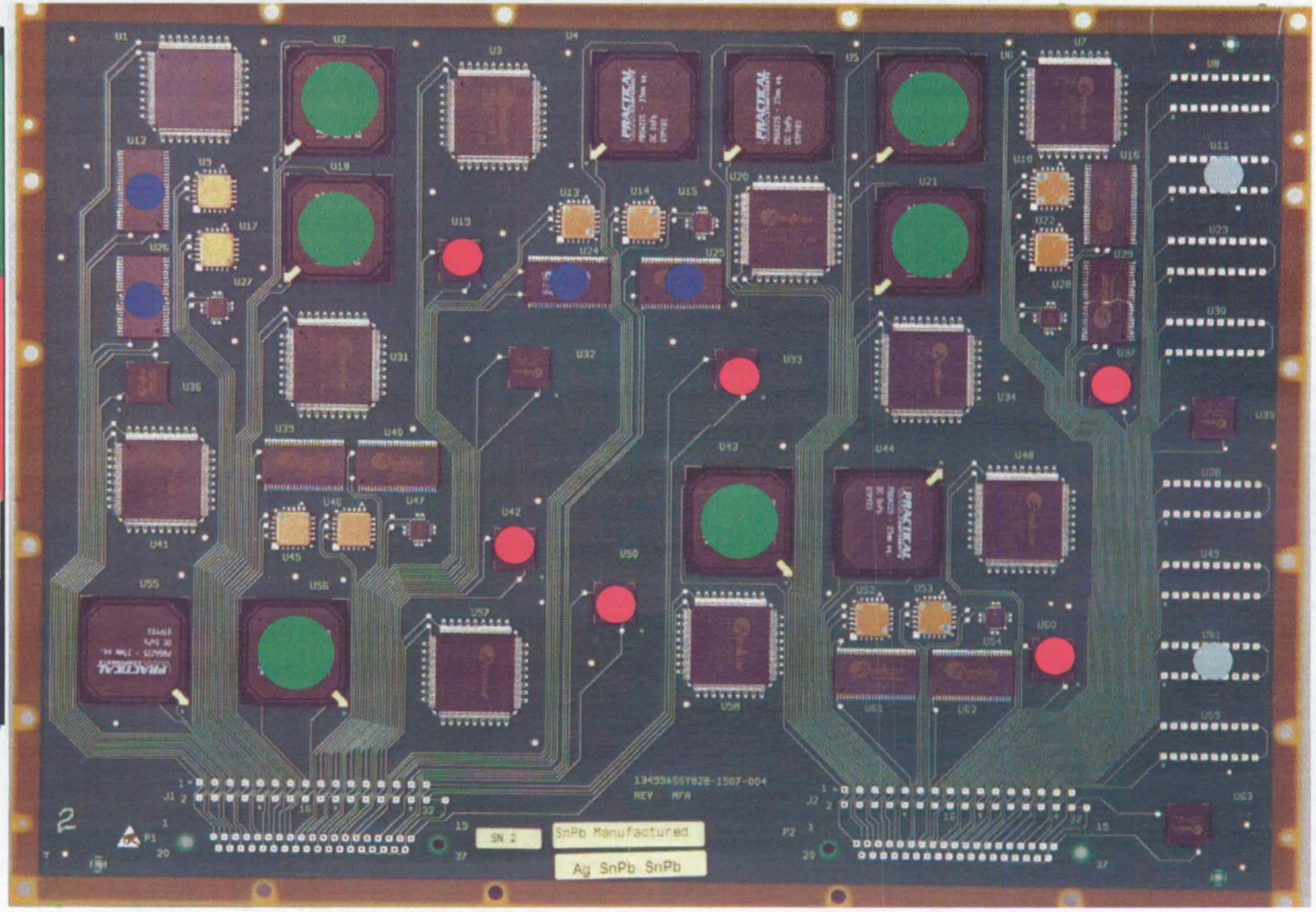
Component Finish/Solder Combinations Example

Lead-Free Manufactured							
Component	Component Finish	Set A			Set B		
		Reflow Solder	Wave Solder	Board Finish	Reflow Solder	Wave Solder	Board Finish
BGA-225	SnPb	SAC305		Immersion Silver ------- A limited Number of Boards will be Built with ENIG	SN100C		Immersion Silver
BGA-225	SAC405	SAC305			SN100C		
CLCC-20	SnPb	SAC305			SN100C		
CLCC-20	SAC305	SAC305			SN100C		
CSP-100	SnPb	SAC305			SN100C		
CSP-100	SAC105	SAC305			SN100C		
PDIP-20	NiPdAu		SN100C			SN100C	
PDIP-20	Sn		SN100C			SN100C	
QFN	Matte Sn	SAC305			SN100C		
TQFP-144	SnPb Dip	SAC305			SN100C		
TQFP-144	Matte Sn	SAC305			SN100C		
TSOP-50	SnPb	SAC305			SN100C		
TSOP-50	SnBi	SAC305			SN100C		

Reflow Profile = SAC305
Preheat = 60-120 seconds @150-190°C
Peak temperature target = 243°C
Reflow: ~20 seconds above 230°C
~30-90 seconds above 220°C

Wave Profile = SN100C
Solder Pot Temperature = 265°C
Preheat Board T = 134°C
Peak Temperature = 157°C
Speed: 90 cm/min

RefDes	Component
U18	BGA-225
U43	BGA-225
U06	BGA-225
U02	BGA-225
U21	BGA-225
U56	BGA-225
U33	CSP-100
U50	CSP-100
U19	CSP-100
U37	CSP-100
U42	CSP-100
U60	CSP-100
U11	PDIP-20
U51	PDIP-20
U12	TSOP-50
U25	TSOP-50
U24	TSOP-50
U26	TSOP-50



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Component Finish/Solder Combinations Example

SnPb Rework						
Component	**Original Component Finish**	**Reflow Solder**	**Wave Solder**	**New Component Finish**	**Rework Solder**	**Board Finish**
BGA-225	SAC405	SnPb				Immersion Silver --- A limited Number of Boards will be Built with ENIG
BGA-225	SnPb	SnPb		SAC405	SnPb	
BGA-225	SnPb	SnPb		SnPb	Flux Only	
CLCC-20	SAC305	SnPb				
CSP-100	SAC105	SnPb				
CSP-100	SnPb	SnPb		SnPb	Flux Only	
CSP-100	SnPb	SnPb		SAC105	SnPb	
PDIP-20	NiPdAu		SnPb			
PDIP-20	Sn		SnPb			
PDIP-20	SnPb		SnPb	Sn	SnPb	
QFN	Matte Sn	SnPb				
TQFP-144	NiPdAu	SnPb				
TQFP-144	SnPb Dip	SnPb				
TSOP-50	Sn	SnPb				
TSOP-50	SnBi	SnPb				
TSOP-50	SnPb	SnPb		SnPb	SnPb	
TSOP-50	SnPb	SnPb		Sn	SnPb	

Profiles used during initial assembly

Reflow Profile = SAC305
Preheat = 60-120 seconds @150-190°C
Peak temperature target = 243°C
Reflow: ~20 seconds above 230°C
~30-90 seconds above 220°C

Wave Profile = SN100C
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Speed: 90 cm/min

National Aeronautics and Space Administration (NASA)

Component Finish/Solder Combinations Example

Lead-Free Rework						
Component	Component Finish	Reflow Solder	Wave Solder	New Component Finish	Rework Solder	Board Finish
BGA-225	SnPb	SAC305				Immersion Silver
BGA-225	SAC405	SAC305		SAC405	SnPb	
BGA-225	SAC405	SAC305		SAC405	Flux Only	
CLCC-20	SnPb	SAC305				
CSP-100	SnPb	SAC305				
CSP-100	SAC405	SAC305				
CSP-100	SAC105	SAC305		SAC105	Flux Only	
CSP-100	SAC105	SAC305		SAC105	SnPb	
PDIP-20	Sn		SN100C			
PDIP-20	Sn		SN100C	Sn	SN100C	
QFN	SnPb	SAC305				
TQFP-144	NiPdAu	SAC305				
TQFP-144	SAC 305 Dip	SAC305				
TSOP-50	SnBi	SAC305				
TSOP-50	SnPb	SAC305				
TSOP-50	Sn	SAC305		Sn	SnPb	
TSOP-50	SnBi	SAC305		SnBi	SAC305	

Profiles used during initial assembly

Reflow Profile = SAC305
Preheat = 60-120 seconds @150-190°C
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Wave Profile = SN100C
Solder Pot Temperature = 265°C
Preheat Board T = 134°C
Peak Temperature = 157°C
Speed: 90 cm/min

Testing Activities

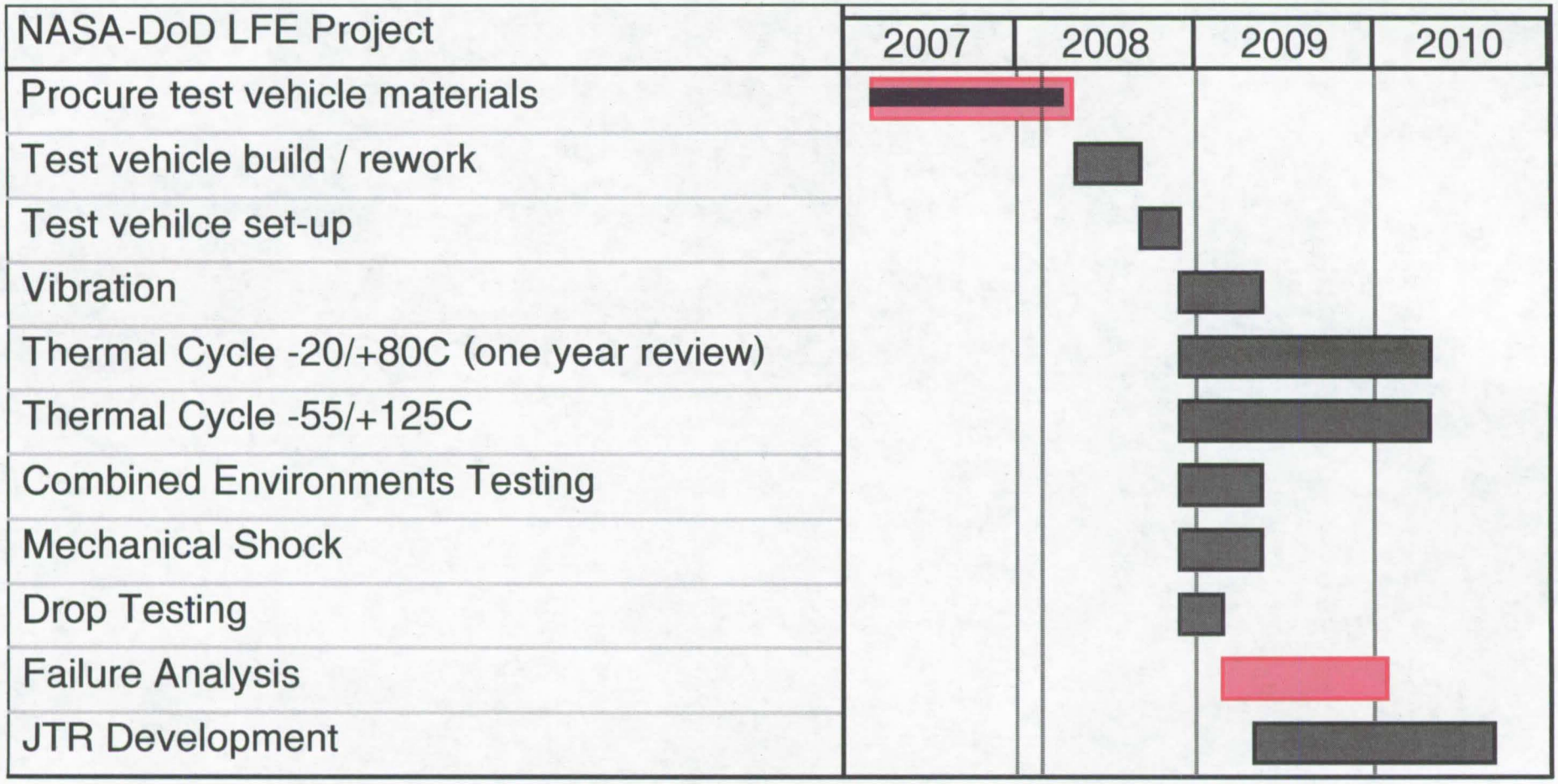
Specific testing details can be found in the Joint Test Protocol (JTP)
http://www.teerm.nasa.gov/reports.html

Thermal Cycling: -20°C to +80°C BOEING	Thermal Cycling: -55°C to +125°C Rockwell Collins	Drop Testing CELESTICA
Vibration BOEING	Mechanical Shock BOEING	Interconnect Stress Testing Interconnect PWB Solutions Inc
Combined Environments Testing Raytheon		Copper Dissolution Rockwell Collins CELESTICA

NAVSEA Crane Rework Effort

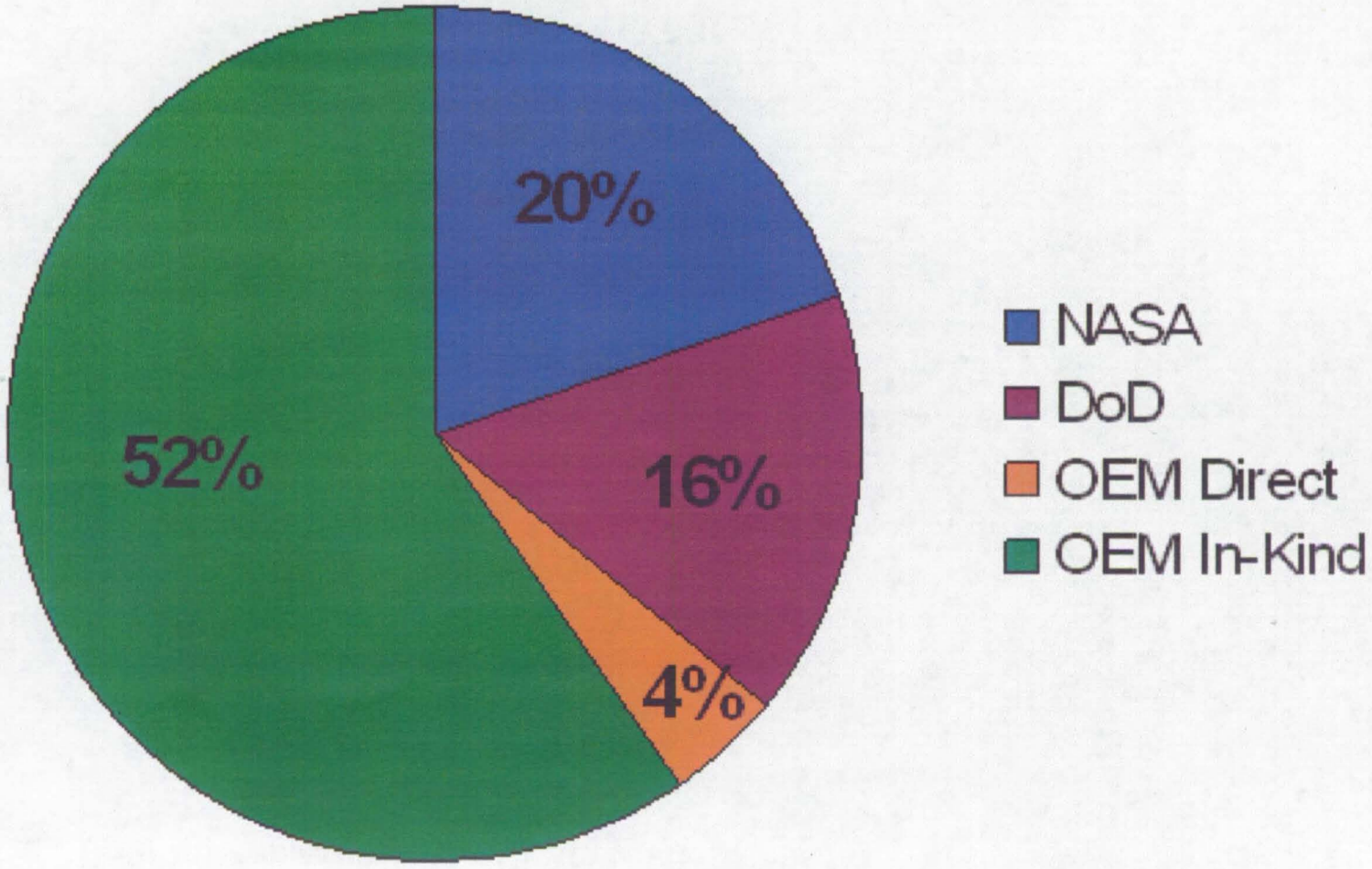
- Build 30 additional test vehicles
  - Test vehicles will be built with Lead-Free solder and Lead-Free component finishes only = similar to Manufactured test vehicles for Mechanical Shock, Vibration and Drop Testing
  - Lead-Free alloys, SAC305 and SN100C
  - Rework will be done using only SnPb solder
  - Perform multiple pass rework 1, 2 and 3 times on random Pb-free DIP, TQFP-144, TSOP-50, LCC and QFN components
  - Testing
    - Thermal Cycling -55°C to +125°C
    - Vibration Testing
    - Drop Testing

NASA-DoD LFE Project Schedule



Individual testing results and conclusions will be released throughout the duration of the project

Contributions to the NASA-DoD Lead-Free Electronics Project ~$1.5 Million



NASA-DoD Project Support

Project Activity	Responsible Party
Procurement	
Procurement of components and boards, includes tinning of component leads	NAVSEA Crane
Component Characterization	
Component Characterization	Rockwell Collins COM DEV Boeing
Assembly	
Surface Mount Assembly and SnPb wave soldering	BAE Systems
Lead-free wave soldering	TT Apsco
Assembly Characterization	
1 test vehicle from each of the 4 test vehicle types assembled	Rockwell Collins
Assembly Inspection	
In-line x-ray evaluation of test vehicle assemblies	Lockheed Martin
Rework	
Extra, Characterization, Vibration and Combined Environments Test Vehicles	BAE Systems
Thermal Cycle, -55 to +125°C and -20 to +80°C Test Vehicles	Lockheed Martin
Mechanical Shock and Drop Testing Test Vehicles	TT Apsco

Project Activity	Responsible Party
Rework Characterization	
1 component from each of the 4 component types (BGA, CSP, PDIP, TSOP) being reworked from each of the 3 types of rework boards (SnPb, SnPb-ENIG, LF).	Rockwell Collins
Thermal Aging	
All test vehicles to be aged, 100°C for 24 hours	BAE Systems
Testing	
Thermal Cycling -55 to +125°C	Rockwell Collins
Thermal Cycling -20 to +80°C	Boeing
Vibration	Boeing
Combined Environments	Raytheon
Drop Testing	Celestica
Mechanical Shock	Boeing / Nihon Superior
Interconnect Stress Testing (IST)	PWB Interconnect Solutions
Failure Analysis	
Micro-section analysis	Celestica
Micro-section analysis	COM DEV
Micro-section analysis	Harris
Micro-section analysis	Lockheed Martin
Micro-section analysis – Thermal Cycle -55 to +125°C	Rockwell Collins
Micro-section analysis	NASA-MSFC

NASA-DoD Lead-Free Electronics Project

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NASA Technology Evaluation Principal Center (TEERM)
Kennedy Space Center, FL
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E-Mail: kurt.r.kessel@nasa.gov
Website: www.teerm.nasa.gov

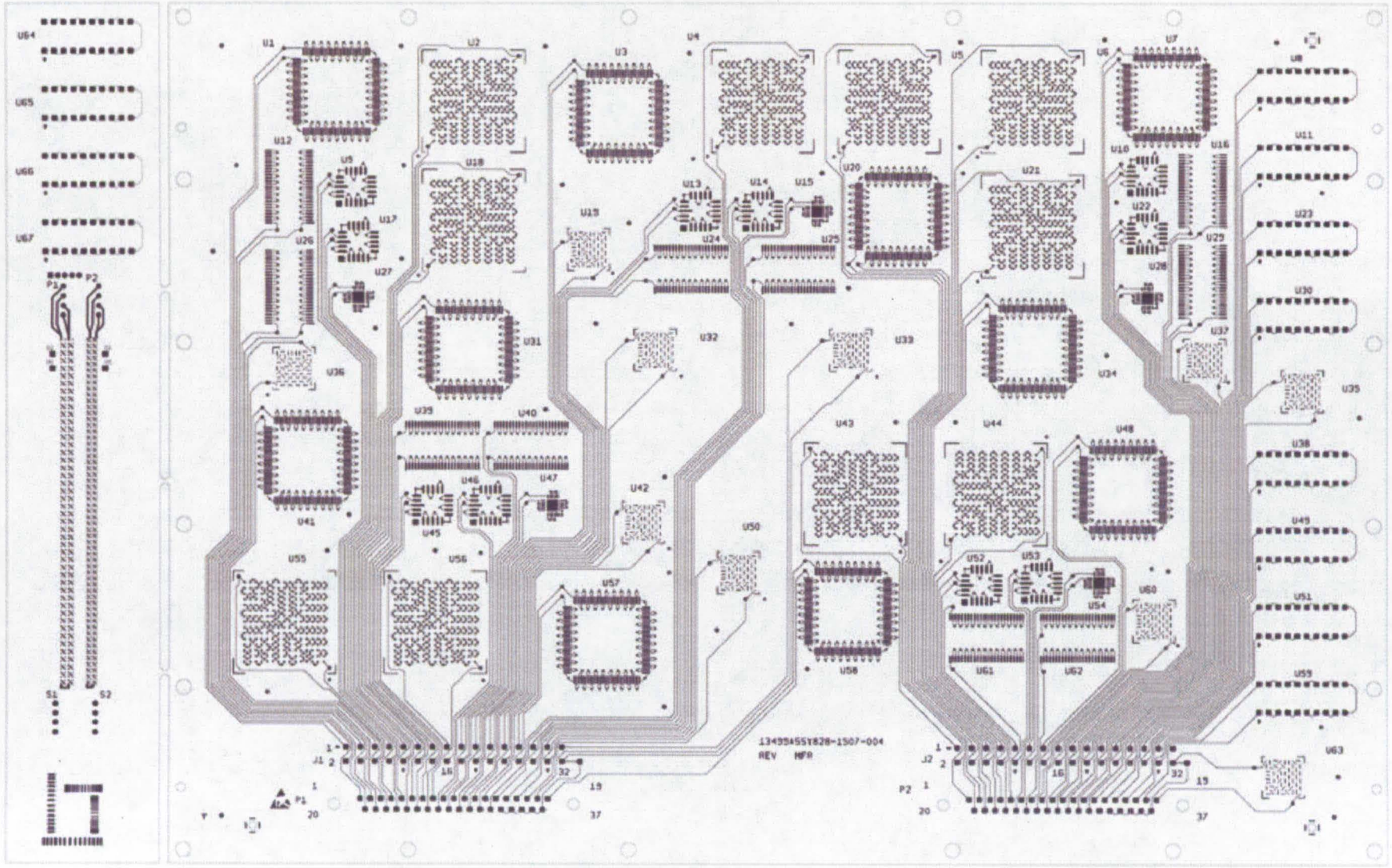
Web Links:

- **NASA-DoD Lead-Free Electronics Project:**
  http://www.teerm.nasa.gov/projects/NASA_DODLeadFreeElectronics_Proj2.html

- **JCAA/JGPP Lead-Free Solder Testing for High Reliability:**
  http://www.teerm.nasa.gov/projects/LeadFreeSolderTestingForHighReliability_Proj1.html

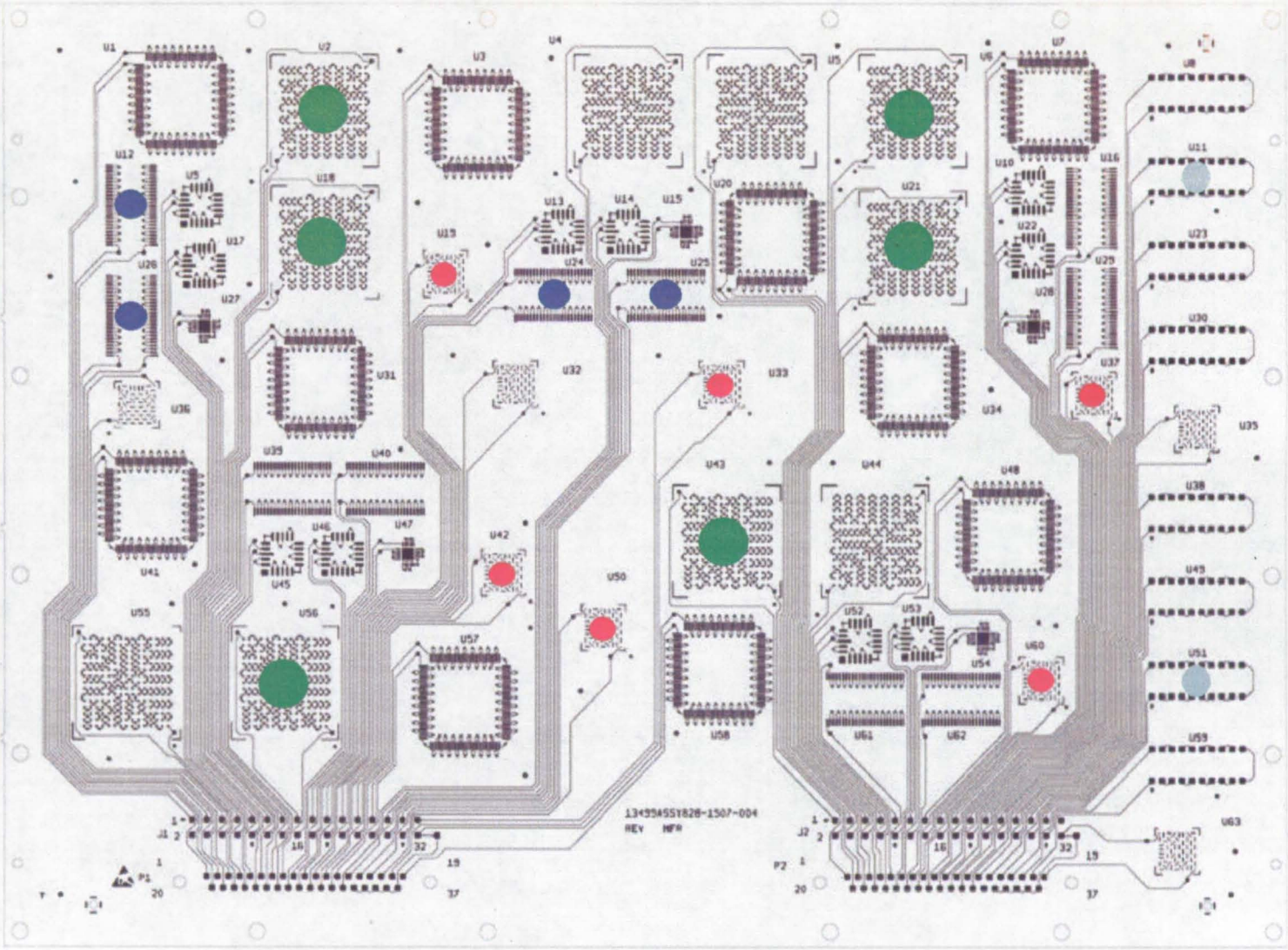
Back-Up Slides

Test Vehicles ~193
(120 Manufactured + 73 Rework)



Components to be Reworked

RefDes	Component
U18	BGA-225
U43	BGA-225
U06	BGA-225
U02	BGA-225
U21	BGA-225
U56	BGA-225
U33	CSP-100
U50	CSP-100
U19	CSP-100
U37	CSP-100
U42	CSP-100
U60	CSP-100
U11	PDIP-20
U51	PDIP-20
U12	TSOP-50
U25	TSOP-50
U24	TSOP-50
U26	TSOP-50



Thermal Cycle -20/+80°C

Parameters	- -20 to +80°C - Cycles: The project consortia will review the data and determine when the test is complete - Decision point 10,000 cycles - 5 to 10°C/minute ramp - 30 minute high temperature dwell - 10 minute low temperature dwell

Number of Test Vehicles Required				
Manufactured		Rework		
Mfg. SnPb	Mfg. LF	Rwk. SnPb	Rwk. SnPb ENIG	Rwk. LF
5	5	5	1	5
Trials per Specimen	1			

Thermal Cycle -55/+125°C

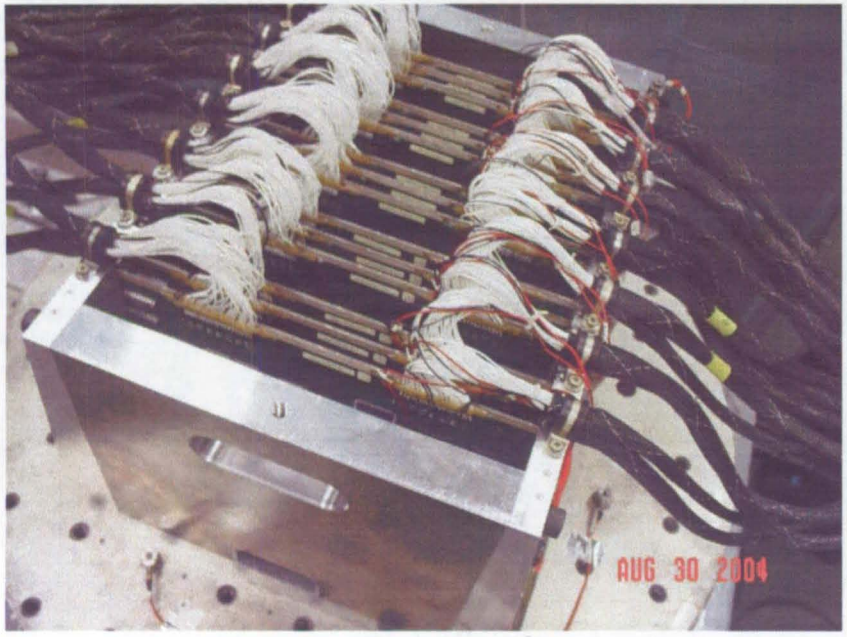
Parameters	- -55 to +125°C - Cycles: The project consortia will review the data and determine when the test is complete - Decision point at 2,000 and 4,000 cycles - 5 to 10°C/minute ramp - 30 minute high temperature dwell - 10 minute low temperature dwell

Rockwell Collins

Number of Test Vehicles Required						
Manufactured				Rework		
Mfg. SnPb	Mfg. LF	Mfg. LF SN100C	Mfg. LF ENIG	Rwk. SnPb	Rwk. SnPb ENIG	Rwk. LF
5	5	5	1	5	1	5
Trials per Specimen	1					

Vibration

Parameters	- Start at 8.0 g_{rms} then step up in 2 g_{rms} increments in the axis perpendicular to the plane of the test vehicles until the 20.0 g_{rms} level is completed. Vibrate for 1 hour at each test level. Finish with 1 hour at 28.0 g_{rms}.					
Number of Test Vehicles Required						
Manufactured				Rework		
Mfg. SnPb	Mfg. LF	Mfg. LF ENIG	Mfg. LF SN100C	Rwk. SnPb	Rwk. SnPb ENIG	Rwk. LF
5	5	1	5	5	1	5
Trials per Specimen			1			



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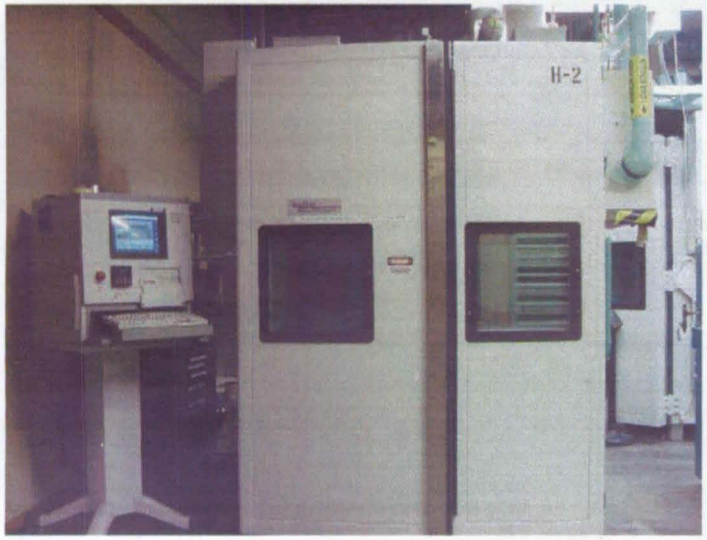
Combine Environments Testing

Parameters	- -55°C to +125°C - Number of cycles ≥ 500 - 20°C/minute ramp - 15 minute soak - Vibration for duration of thermal cycle - 10 G_{rms}, initial - Increase 5 Grms after every 50 cycles - 55 G_{rms}, maximum					
Number of Test Vehicles Required						
Manufactured				Rework		
Mfg. SnPb	Mfg. LF	Mfg. LF SN100C	Mfg. LF ENIG	Rwk. SnPb	Rwk. SnPb ENIG	Rwk. LF
5	5	5	1	5	1	5
Trials per Specimens	1					

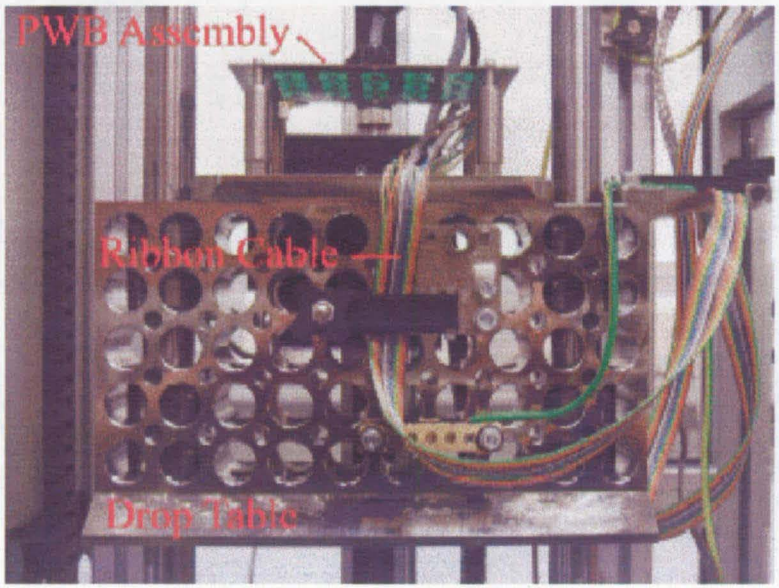
Raytheon



Drop Testing

Parameters	- Shock testing will be conducted in the -Z direction - 340Gpk input, 2ms pulse duration - Test vehicles will be dropped until all monitored components fail or 10 drops have been completed				
Number of Test Vehicles Required					
Manufactured		Rework			
Mfg. SnPb	Mfg. LF	Rwk. SnPb	Rwk. SnPb ENIG	Rwk. LF	
5	5	5	1	5	
Trials per Specimen	A maximum of 10 drops				

CELESTICA



Mechanical Shock

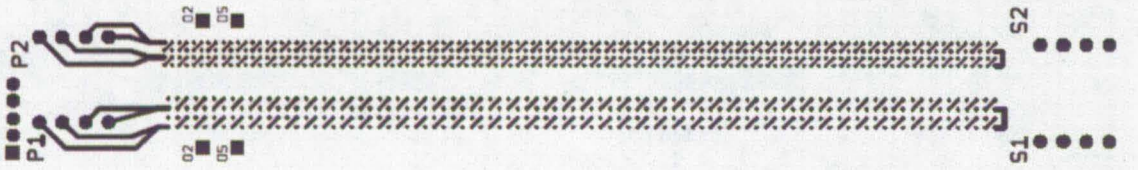
Parameters	The shock transients will be applied perpendicular to the plane of the board and will be increased after every 100 shocks (i.e., a step stress test). Frequency range is 40 to 1000 Hz. SRS damping: 5%			
	Test Shock Response Spectra	Amplitude (G's)	Te (msec)	Shocks per Level
	Modified Functional Test for Flight Equipment (Level 1)	20	<30	100
	Modified Functional Test for Ground Equipment (Level 2)	40	<30	100
	Modified Crash Hazard Test for Ground Equipment (Level 3)	75	<30	100
	Level 4	100	<30	100
	Level 5	200	<30	100
	Level 6	300	<30	100
	Level 7	500	<30	100
	Level 8	700	<30	100

Number of Test Vehicles Required				
Manufactured		Rework		
Mfg. SnPb	Mfg. LF	Rwk. SnPb	Rwk. SnPb ENIG	Rwk. LF
5	5	5	1	5
Trials per Specimen		1		

BOEING

Interconnect Stress Test (IST)

- Accelerates thermal cycling testing by heating a specifically designed test coupon to 150°C (higher temperatures in specific applications in exactly 3 minutes followed by cooling to ambient in approximately two minutes.
- Assembly and rework simulation is achieved by subjecting the coupon to heating to 230°C (260°C for lead-free applications) in three minutes followed by cooling to ambient in approximately 2 minutes.
  - Three thermal cycles simulate assembly
  - Six thermal cycles simulate assembly and rework

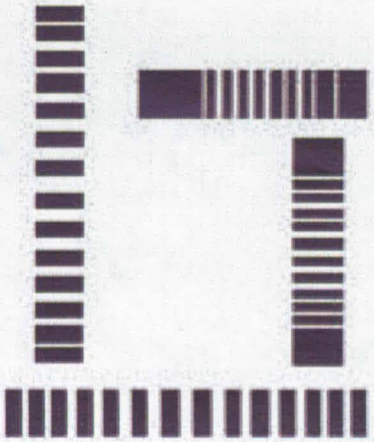


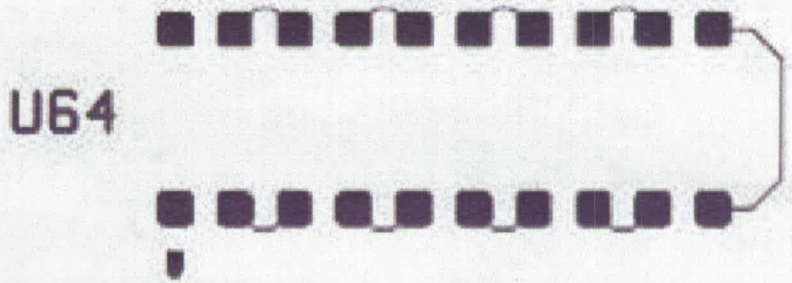
Interconnect PWB Solutions Inc.

Copper Dissolution

Parameters	▪Mini-wave soldering versus manual soldering ▪Number of component removals: 1X versus 3X ▪PDIPS on break off coupon and QFP pad pattern ▪Metallographic Analysis: •As fabricated copper thickness •As assembled copper thickness •As reworked copper thickness

Number of Test Vehicles Break off Coupons Required					
Manufactured			Rework		
Mfg. SnPb	Mfg. LF	Mfg. LF SN100C	Rwk. SnPb	Rwk. SnPb ENIG	Rwk. LF
5	5	5	5	1	5





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